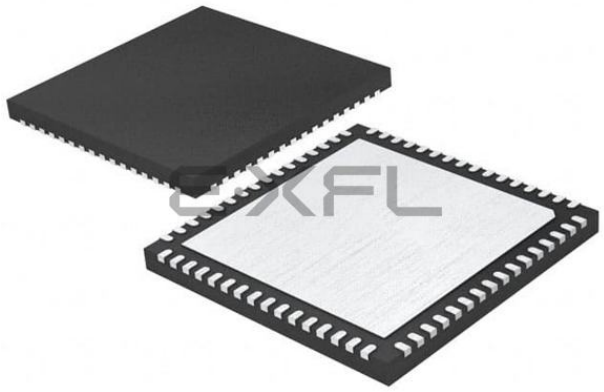

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	64MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (64K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f67k90-e-mr

TABLE 1-4: PIC18F8XK90 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTG is a bidirectional I/O port.
RG0/ECCP3/P3A	5			
RG0		I/O	ST	Digital I/O.
ECCP3		I/O	ST	Capture 3 input/Compare 3 output/PWM3 output.
P3A		O	—	ECCP3 PWM Output A.
RG1/TX2/CK2/AN19/ C3OUT	6			
RG1		I/O	ST	Digital I/O.
TX2		O	—	EUSART asynchronous transmit.
CK2		I/O	ST	EUSART synchronous clock (see related RX2/DT2).
AN19		I	Analog	Analog Input 19.
C3OUT		O	—	Comparator 3 output.
RG2/RX2/DT2/AN18/ C3INA	7			
RG2		I/O	ST	Digital I/O.
RX2		I	ST	EUSART asynchronous receive.
DT2		I/O	ST	EUSART synchronous data (see related TX2/CK2).
AN18		I	Analog	Analog Input 18.
C3INA		I	Analog	Comparator 3 Input A.
RG3/CCP4/AN17/P3D/ C3INB	8			
RG3		I/O	ST	Digital I/O.
CCP4		I/O	ST	Capture 4 input/Compare 4 output/PWM4 output.
AN17		I	Analog	Analog Input 17.
P3D		O	—	ECCP3 PWM Output D.
C3INB		I	Analog	Comparator 3 Input B.
RG4/SEG26/RTCC/ T7CKI/T5G/CCP5/AN16/ P1D/C3INC	10			
RG4		I/O	ST	Digital I/O.
SEG26		O	Analog	SEG26 output for LCD.
RTCC		O	—	RTCC output.
T7CKI(3)		I	ST	Timer7 clock input.
T5G		I	ST	Timer5 external clock gate input.
CCP5		I/O	ST	Capture 5 input/Compare 5 output/PWM5 output.
AN16		I	Analog	Analog Input 16.
P1D		O	—	ECCP1 PWM Output D.
C3INC		I	Analog	Comparator 3 Input C.
RG5	9			See the $\overline{\text{MCLR}}$/RG5 pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to V_{DD}); I^2C™ = I^2C/SMBus

Note 1: Default assignment for ECCP2 when the CCP2MX Configuration bit is set.
2: Alternate assignment for ECCP2 when the CCP2MX Configuration bit is cleared.
3: Not available on PIC18F65K90 and PIC18F85K90 devices.
4: The CCP6, CCP7, CCP8 and CCP9 pin placement depends on the ECCPMX Configuration bit setting.

TABLE 5-2: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

Register	Applicable Devices		Power-on Reset, Brown-out Reset	$\overline{\text{MCLR}}$ Resets, WDT Reset, RESET Instruction, Stack Resets, CM Resets	Wake-up via WDT or Interrupt
SSP2CON2	PIC18F6XK90	PIC18F8XK90	0000 0000	0000 0000	uuuu uuuu
LCDREF	PIC18F6XK90	PIC18F8XK90	0000 0000	0000 0000	uuuu uuuu
LCDRL	PIC18F6XK90	PIC18F8XK90	0000 -000	0000 -000	uuuu -uuu
LCDSE5	PIC18F6XK90	PIC18F8XK90	0000 0000	0000 0000	uuuu uuuu
LCDSE4	PIC18F6XK90	PIC18F8XK90	---- ---0	---- ---u	---- ---u
LCDSE4	PIC18F6XK90	PIC18F8XK90	0000 0000	uuuu uuuu	uuuu uuuu
LCDSE3	PIC18F6XK90	PIC18F8XK90	0000 0000	uuuu uuuu	uuuu uuuu
LCDSE2	PIC18F6XK90	PIC18F8XK90	0000 0000	uuuu uuuu	uuuu uuuu
LCDSE1	PIC18F6XK90	PIC18F8XK90	0000 0000	uuuu uuuu	uuuu uuuu
LCDSE0	PIC18F6XK90	PIC18F8XK90	0000 0000	uuuu uuuu	uuuu uuuu
LCDPS	PIC18F6XK90	PIC18F8XK90	0000 0000	0000 0000	uuuu uuuu
LCDCON	PIC18F6XK90	PIC18F8XK90	000- 0000	000- 0000	uuu- uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition. Shaded cells indicate conditions do not apply for the designated device.

Note 1: When the wake-up is due to an interrupt, and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.

2: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

3: One or more bits in the INTCONx or PIRx registers will be affected (to cause wake-up).

4: See Table 5-1 for the Reset value for a specific condition.

NOTES:

REGISTER 10-11: PIE2: PERIPHERAL INTERRUPT ENABLE REGISTER 2

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OSCFIE	—	SSP2IE	BCL2IE	BCL1IE	HLVDIE	TMR3IE	TMR3GIE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **OSCFIE:** Oscillator Fail Interrupt Enable bit
1 = Enabled
0 = Disabled

bit 6 **Unimplemented:** Read as '0'

bit 5 **SSP2IE:** Master Synchronous Serial Port 2 Interrupt Enable bit
1 = Enables the MSSP interrupt
0 = Disables the MSSP interrupt

bit 4 **BCL2IE:** Bus Collision Interrupt Enable bit
1 = Enables the bus collision interrupt
0 = Disables the bus collision interrupt

bit 3 **BCL1IE:** Bus Collision Interrupt Enable bit
1 = Enabled
0 = Disabled

bit 2 **HLVDIE:** High/Low-Voltage Detect Interrupt Enable bit
1 = Enabled
0 = Disabled

bit 1 **TMR3IE:** TMR3 Overflow Interrupt Enable bit
1 = Enabled
0 = Disabled

bit 0 **TMR3GIE:** Timer3 Gate Interrupt Enable bit
1 = Enabled
0 = Disabled

REGISTER 10-18: IPR3: PERIPHERAL INTERRUPT PRIORITY REGISTER 3

R/W-1	R/W-1	R-1	R-1	R/W-1	R/W-1	R/W-1	R/W-1
TMR5GIP	LCDIP	RC2IP	TX2IP	CTMUIP	CCP2IP	CCP1IP	RTCCIP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **TMR5GIP:** Timer5 Gate interrupt Priority bit
1 = High priority
0 = Low priority

bit 6 **LCDIP:** LCD Interrupt Priority bit (valid when the Type-B waveform with Non-Static mode is selected)
1 = High priority
0 = Low priority

bit 5 **RC2IP:** AUSART Receive Priority Flag bit
1 = High priority
0 = Low priority

bit 4 **TX2IP:** AUSART Transmit Interrupt Priority bit
1 = High priority
0 = Low priority

bit 3 **CTMUIP:** CTMU Interrupt Priority bit
1 = High priority
0 = Low priority

bit **CCP2IP:** ECCP2 Interrupt Priority bit
1 = High priority
0 = Low priority

bit **CCP1IP:** ECCP1 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 0 **RTCCIP:** RTCC Interrupt Priority bit
1 = High priority
0 = Low priority

REGISTER 10-19: IPR4: PERIPHERAL INTERRUPT PRIORITY REGISTER 4

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
CCP10IP(1)	CCP9IP(1)	CCP8IP	CCP7IP	CCP6IP	CCP5IP	CCP4IP	CCP3IP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **CCP10IP:CCP3IP:** CCP<10:3> Interrupt Priority bits(1)
1 = High priority
0 = Low priority

Note 1: CCP10IP and CCP9IP are unimplemented in devices with a program memory of 32 Kbytes (PIC18FX5K90).

TABLE 11-16: PORTH FUNCTIONS

Pin Name	Function	TRIS Setting	I/O	I/O Type	Description
RH0/SEG47/ AN23	RH0	0	O	DIG	LATH<0> data output.
		1	I	ST	PORTH<0> data input.
	SEG47	1	O	ANA	LCD Segment 47 output; disables all other pin functions.
	AN23	1	I	ANA	A/D Input Channel 23. Default input configuration on POR; does not affect digital input.
RH1/SEG46/ AN22	RH1	0	O	DIG	LATH<1> data output.
		1	I	ST	PORTH<1> data input.
	SEG46	1	O	ANA	LCD Segment 46 output; disables all other pin functions.
	AN22	1	I	ANA	A/D Input Channel 22. Default input configuration on POR; does not affect digital input.
RH2/SEG45/ AN21	RH2	0	O	DIG	LATH<2> data output.
		1	I	ST	PORTH<2> data input.
	SEG45	1	O	ANA	LCD Segment 45 output; disables all other pin functions.
	AN21	1	I	ANA	A/D Input Channel 21. Default input configuration on POR; does not affect digital input.
RH3/SEG44/ AN20	RH3	0	O	DIG	LATH<3> data output.
		1	I	ST	PORTH<3> data input.
	SEG44	1	O	ANA	LCD Segment 44 output; disables all other pin functions.
	AN20	1	I	ANA	A/D Input Channel 20. Default input configuration on POR; does not affect digital input.
RH4/SEG40/ CCP9/P3C/ AN12/C2INC	RH4	0	O	DIG	LATH<4> data output.
		1	I	ST	PORTH<4> data input.
	SEG40	1	O	ANA	LCD Segment 40 output; disables all other pin functions.
	CCP9	0	O	DIG	CCP9 compare/PWM output; takes priority over port data.
		1	I	ST	CCP9 capture input.
	P3C	0	O	—	ECCP3 PWM Output C. May be configured for tri-state during Enhanced PWM.
	AN12	1	I	ANA	A/D Input Channel 12. Default input configuration on POR; does not affect digital input.
	C2INC	x	I	ANA	Comparator 2 Input C.
RH5/SEG41/ CCP8/P3B/ AN13/C2IND	RH5	0	O	DIG	LATH<5> data output.
		1	I	ST	PORTH<5> data input.
	SEG41	1	O	ANA	LCD Segment 41 output; disables all other pin functions.
	CCP8	0	O	DIG	CCP8 compare/PWM output; takes priority over port data.
		1	I	ST	CCP8 capture input.
	P3B	0	O	—	ECCP3 PWM Output B. May be configured for tri-state during Enhanced PWM.
	AN13	1	I	ANA	A/D Input Channel 13. Default input configuration on POR; does not affect digital input.
	C2IND	x	I	ANA	Comparator 2 Input D.

Legend: O = Output, I = Input, ANA = Analog Signal, DIG = Digital Output, ST = Schmitt Trigger Buffer Input, x = Don't care (TRIS bit does not affect port direction or is overridden for this option).

NOTES:

21.4.3.2 Address Masking Modes

Masking an address bit causes that bit to become a "don't care". When one address bit is masked, two addresses will be Acknowledged and cause an interrupt. It is possible to mask more than one address bit at a time, which greatly expands the number of addresses Acknowledged.

The I^2C slave behaves the same way whether address masking is used or not. However, when address masking is used, the I^2C slave can Acknowledge multiple addresses and cause interrupts. When this occurs, it is necessary to determine which address caused the interrupt by checking the SSPxBUF.

The PIC18F87K90 family of devices is capable of using two different Address Masking modes in I^2C slave operation: 5-Bit Address Masking and 7-Bit Address Masking. The Masking mode is selected at device configuration using the MSSPMSK Configuration bit. The default device configuration is 7-Bit Address Masking.

Both Masking modes, in turn, support address masking of 7-bit and 10-bit addresses. The combination of Masking modes and addresses provide different ranges of Acknowledgable addresses for each combination.

While both Masking modes function in roughly the same manner, the way they use address masks are different.

21.4.3.3 5-Bit Address Masking Mode

As the name implies, 5-Bit Address Masking mode uses an address mask of up to 5 bits to create a range of addresses to be Acknowledged, using bits, 5 through 1, of the incoming address. This allows the module to Acknowledge up to 31 addresses when using 7-bit addressing, or 63 addresses with 10-bit addressing (see Example 21-2). This Masking mode is selected when the MSSPMSK Configuration bit is programmed ('0').

The address mask in this mode is stored in the SSPxCON2 register, which stops functioning as a control register in I^2C Slave mode (Register 21-6). In 7-Bit Address Masking mode, address mask bits, ADMSK<5:1> (SSPxCON2<5:1>), mask the corresponding address bits in the SSPxADD register. For any ADMSK bits that are set (ADMSK<n> = 1), the corresponding address bit is ignored (SSPxADD<n> = x). For the module to issue an address Acknowledge, it is sufficient to match only on addresses that do not have an active address mask.

In 10-Bit Address Masking mode, bits, ADMSK<5:2>, mask the corresponding address bits in the SSPxADD register. In addition, ADMSK1 simultaneously masks the two LSbs of the address (SSPxADD<1:0>). For any ADMSK bits that are active (ADMSK<n> = 1), the corresponding address bit is ignored (SPxADD<n> = x). Also note, that although in 10-Bit Address Masking mode, the upper address bits reuse part of the SSPxADD register bits. The address mask bits do not interact with those bits; they only affect the lower address bits.

Note 1: ADMSK1 masks the two Least Significant bits of the address.

2: The two Most Significant bits of the address are not affected by address masking.

EXAMPLE 21-2: ADDRESS MASKING EXAMPLES IN 5-BIT MASKING MODE

7-Bit Addressing:

SSPxADD<7:1>= A0h (1010000) (SSPxADD<0> is assumed to be '0')

ADMSK<5:1> = 00111

Addresses Acknowledged: A0h, A2h, A4h, A6h, A8h, AAh, ACh, AEh

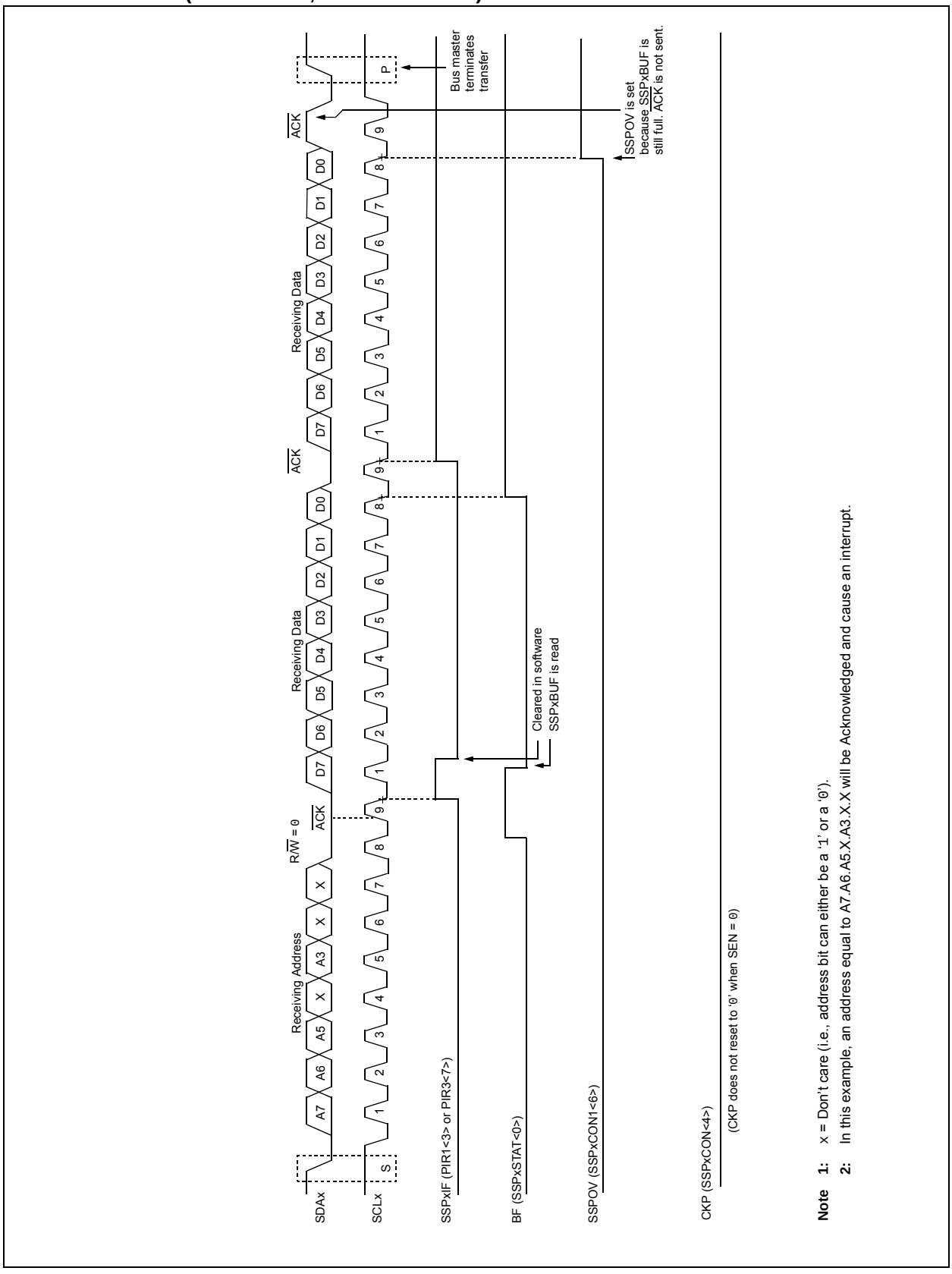
10-Bit Addressing:

SSPxADD<7:0> = A0h (10100000) (The two MSb of the address are ignored in this example, since they are not affected by masking)

ADMSK<5:1> = 00111

Addresses Acknowledged: A0h, A1h, A2h, A3h, A4h, A5h, A6h, A7h, A8h, A9h, AAh, ABh, ACh, ADh, AEh, AFh

FIGURE 21-9: I²C™ SLAVE MODE TIMING WITH SEN = 0 AND ADMSK<5:1> = 01011 (RECEPTION, 7-BIT ADDRESS)



Note 1: x = Don't care (i.e., address bit can either be a '1' or a '0').
2: In this example, an address equal to A7.A6.A5.X.A3.X.X will be Acknowledged and cause an interrupt.

TABLE 22-3: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

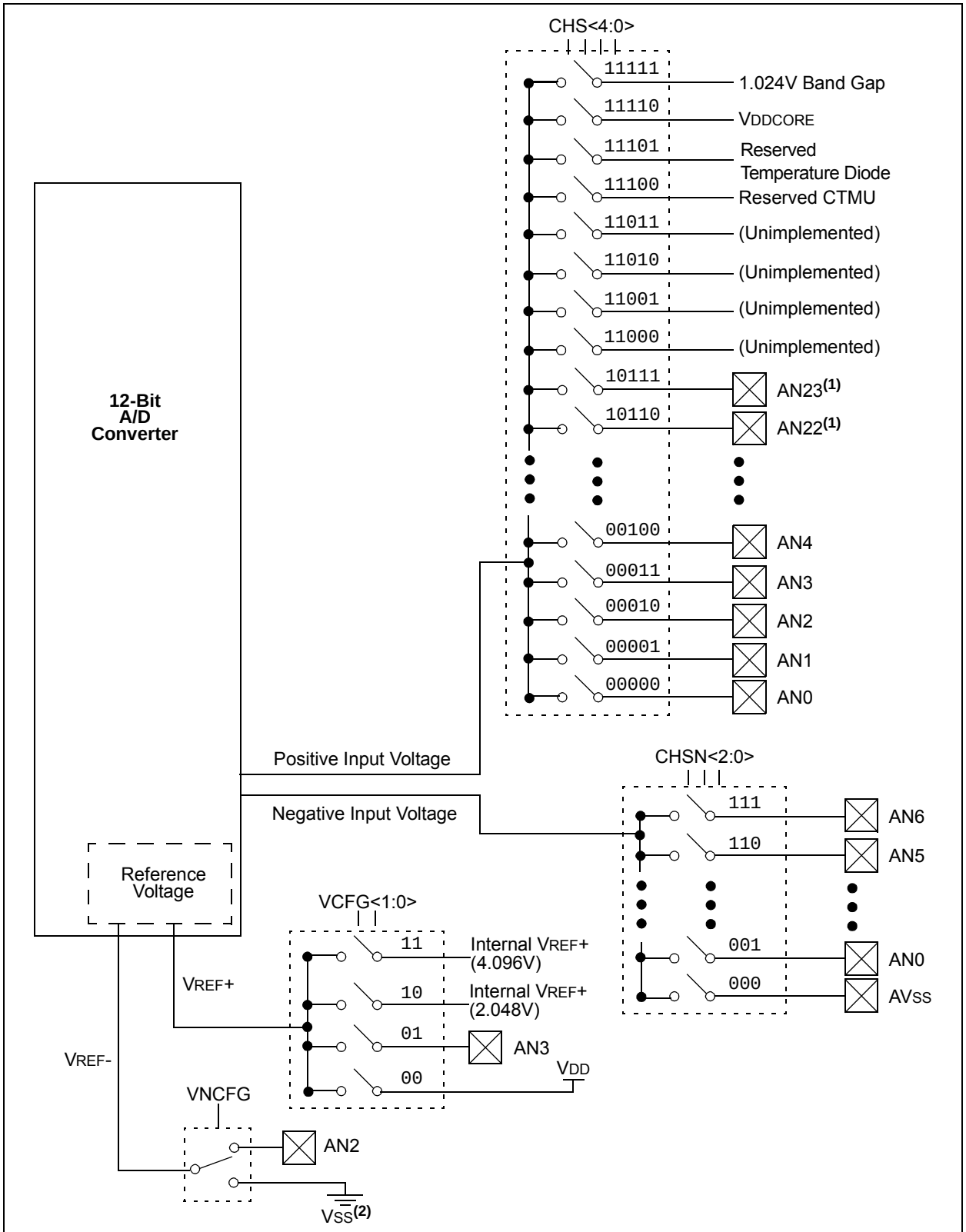
BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 1											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.00	8332	0.300	0.02	4165	0.300	0.02	2082	0.300	-0.04	1665
1.2	1.200	0.02	2082	1.200	-0.03	1041	1.200	-0.03	520	1.201	-0.16	415
2.4	2.402	0.06	1040	2.399	-0.03	520	2.404	0.16	259	2.403	-0.16	207
9.6	9.615	0.16	259	9.615	0.16	129	9.615	0.16	64	9.615	-0.16	51
19.2	19.231	0.16	129	19.231	0.16	64	19.531	1.73	31	19.230	-0.16	25
57.6	58.140	0.94	42	56.818	-1.36	21	56.818	-1.36	10	55.555	3.55	8
115.2	113.636	-1.36	21	113.636	-1.36	10	125.000	8.51	4	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 1								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.04	832	0.300	-0.16	415	0.300	-0.16	207
1.2	1.202	0.16	207	1.201	-0.16	103	1.201	-0.16	51
2.4	2.404	0.16	103	2.403	-0.16	51	2.403	-0.16	25
9.6	9.615	0.16	25	9.615	-0.16	12	—	—	—
19.2	19.231	0.16	12	—	—	—	—	—	—
57.6	62.500	8.51	3	—	—	—	—	—	—
115.2	125.000	8.51	1	—	—	—	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.00	33332	0.300	0.00	16665	0.300	0.00	8332	0.300	-0.01	6665
1.2	1.200	0.00	8332	1.200	0.02	4165	1.200	0.02	2082	1.200	-0.04	1665
2.4	2.400	0.02	4165	2.400	0.02	2082	2.402	0.06	1040	2.400	-0.04	832
9.6	9.606	0.06	1040	9.596	-0.03	520	9.615	0.16	259	9.615	-0.16	207
19.2	19.193	-0.03	520	19.231	0.16	259	19.231	0.16	129	19.230	-0.16	103
57.6	57.803	0.35	172	57.471	-0.22	86	58.140	0.94	42	57.142	0.79	34
115.2	114.943	-0.22	86	116.279	0.94	42	113.636	-1.36	21	117.647	-2.12	16

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.01	3332	0.300	-0.04	1665	0.300	-0.04	832
1.2	1.200	0.04	832	1.201	-0.16	415	1.201	-0.16	207
2.4	2.404	0.16	415	2.403	-0.16	207	2.403	-0.16	103
9.6	9.615	0.16	103	9.615	-0.16	51	9.615	-0.16	25
19.2	19.231	0.16	51	19.230	-0.16	25	19.230	-0.16	12
57.6	58.824	2.12	16	55.555	3.55	8	—	—	—
115.2	111.111	-3.55	8	—	—	—	—	—	—

FIGURE 23-4: A/D BLOCK DIAGRAM



Note 1: Channels, AN12 through AN15, and AN20 through AN23, are not available on 64-pin devices.
2: I/O pins have diode protection to VDD and VSS.

REGISTER 24-1: CMxCON: COMPARATOR CONTROL x REGISTER

R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
CON	COE	CPOL	EVPOL1	EVPOL0	CREF	CCH1	CCH0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **CON:** Comparator Enable bit
1 = Comparator is enabled
0 = Comparator is disabled

bit 6 **COE:** Comparator Output Enable bit
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 5 **CPOL:** Comparator Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 4-3 **EVPOL<1:0>:** Interrupt Polarity Select bits
11 = Interrupt generation on any change of the output(1)
10 = Interrupt generation only on high-to-low transition of the output
01 = Interrupt generation only on low-to-high transition of the output
00 = Interrupt generation is disabled

bit 2 **CREF:** Comparator Reference Select bit (non-inverting input)
1 = Non-inverting input connects to the internal CV_{REF} voltage
0 = Non-inverting input connects to the CxINA pin

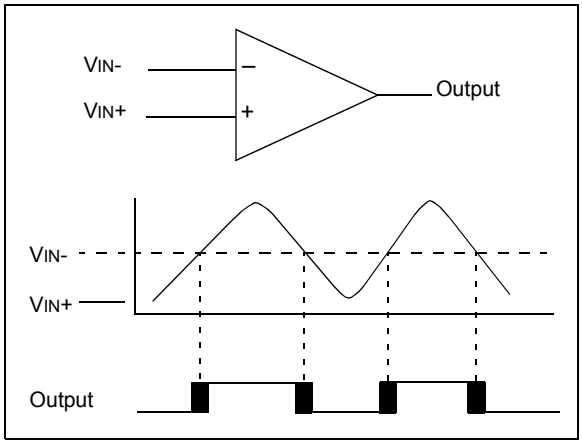
bit 1-0 **CCH<1:0>:** Comparator Channel Select bits
11 = Inverting input of the comparator connects to V_{BG}
10 = Inverting input of the comparator connects to the C2INB or C2IND pin(2,3)
01 = Inverting input of the comparator connects to the CxINC pin(3)
00 = Inverting input of the comparator connects to the CxINB pin

Note 1: The CMPxIF bit is automatically set any time this mode is selected and must be cleared by the application after the initial configuration.
2: Comparators, 1 and 3, use C2INB as an input to the inverting terminal; Comparator 2 uses C2IND.
3: C1INC, C2INC and C2IND are all unavailable for 64-pin devices (PIC18F6XK90).

24.2 Comparator Operation

A single comparator is shown in Figure 24-2, along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input, VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input, VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator, in Figure 24-2, represent the uncertainty due to input offsets and response time.

FIGURE 24-2: SINGLE COMPARATOR



24.3 Comparator Response Time

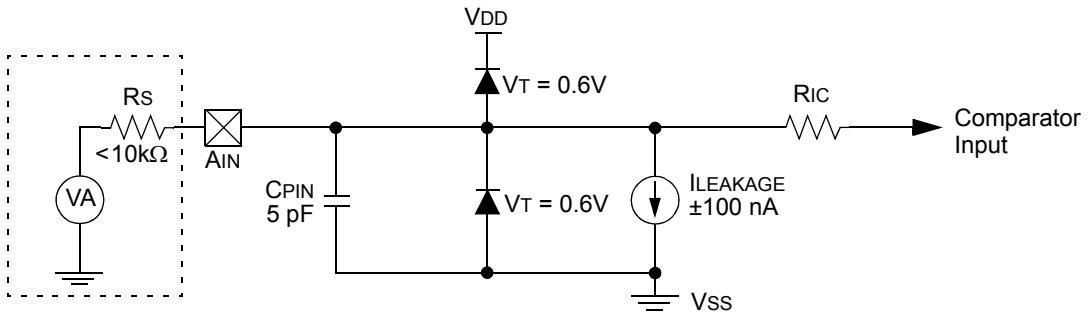
Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output has a valid level. The response time of the comparator differs from the settling time of the voltage reference. Therefore, both of these times must be considered when determining the total response to a comparator input change. Otherwise, the maximum delay of the comparators should be used (see **Section 31.0 "Electrical Characteristics"**).

24.4 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 24-3. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and VSS. The analog input, therefore, must be between VSS and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up condition may occur.

A maximum source impedance of 10 kΩ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 24-3: COMPARATOR ANALOG INPUT MODEL



Legend:

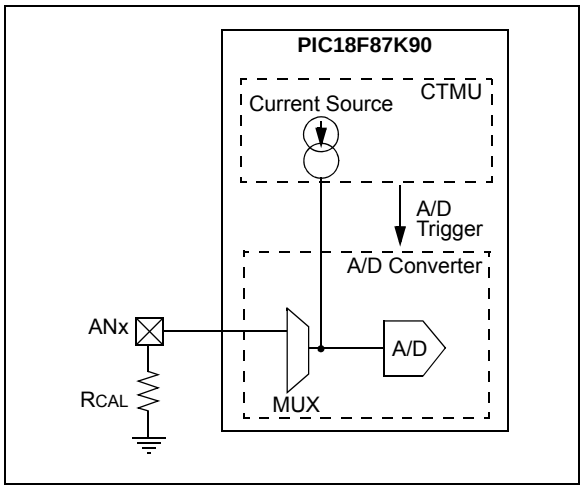
CPIN	=	Input Capacitance
VT	=	Threshold Voltage
ILEAKAGE	=	Leakage Current at the pin due to various junctions
RIC	=	Interconnect Resistance
RS	=	Source Impedance
VA	=	Analog Voltage

The CTMU current source may be trimmed with the trim bits in CTMUICON using an iterative process to get the exact current desired. Alternatively, the nominal value without adjustment may be used. That value may be stored by software for use in all subsequent capacitive or time measurements.

To calculate the value for RCAL, the nominal current must be chosen. Then, the resistance can be calculated.

For example, if the A/D Converter reference voltage is 3.3V, use 70% of full scale (or 2.31V) as the desired approximate voltage to be read by the A/D Converter. If the range of the CTMU current source is selected to be 0.55 μA, the resistor value needed is calculated as, RCAL = 2.31V/0.55 μA, for a value of 4.2 MΩ. Similarly, if the current source is chosen to be 5.5 μA, RCAL would be 420,000Ω, and 42,000Ω if the current source is set to 55 μA.

FIGURE 27-2: CTMU CURRENT SOURCE CALIBRATION CIRCUIT



A value of 70% of full-scale voltage is chosen to make sure that the A/D Converter was in a range that is well above the noise floor. If an exact current is chosen to incorporate the trimming bits from CTMUICON, the resistor value of RCAL may need to be adjusted accordingly. RCAL may also be adjusted to allow for available resistor values. RCAL should be of the highest precision available, in light of the precision needed for the circuit that the CTMU will be measuring. A recommended minimum would be 0.1% tolerance.

The following examples show a typical method for performing a CTMU current calibration.

- Example 27-1 demonstrates how to initialize the A/D Converter and the CTMU.

  This routine is typical for applications using both modules.

- Example 27-2 demonstrates one method for the actual calibration routine.

  This method manually triggers the A/D Converter to demonstrate the entire step-wise process. It is also possible to automatically trigger the conversion by setting the CTMU's CTTRIG bit (CTMUCONH<0>).

XORWF **Exclusive OR W with f**

Syntax: XORWF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (W) .XOR. (f) → dest

Status Affected: N, Z

Encoding:

0001	10da	ffff	ffff

Description: Exclusive OR the contents of W with register 'f'. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in the register 'f'.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 29.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `XORWF REG, 1, 0`

Before Instruction
REG = AFh
W = B5h
After Instruction
REG = 1Ah
W = B5h

30.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

30.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, preprocessor, and one-step driver, and can run on multiple platforms.

30.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

30.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

30.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

31.2 DC Characteristics: Power-Down and Supply Current PIC18F87K90 Family (Industrial/Extended) (Continued)

PIC18F87K90 Family		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD) Cont.(2,3)						
	All devices	3.7	8.5	µA	-40°C	VDD = 1.8V(4) Regulator Disabled	FOSC = 32 kHz(3) (**SEC_RUN** mode, SOSCSEL = 01)
		5.4	10	µA	+25°C		
		6.6	13	µA	+85°C		
		13	30	µA	+125°C		
	All devices	8.7	18	µA	-40°C	VDD = 3.3V(4) Regulator Disabled	
		10	20	µA	+25°C		
		12	23	µA	+85°C		
		25	60	µA	+125°C		
	All devices	60	160	µA	-40°C	VDD = 5V(5) Regulator Enabled	
		90	190	µA	+25°C		
		100	240	µA	+85°C		
		200	450	µA	+125°C		
	All devices	1.2	4	µA	-40°C	VDD = 1.8V(4) Regulator Disabled	FOSC = 32 kHz(3) (**SEC_IDLE** mode, SOSCSEL = 01)
		1.7	5	µA	+25°C		
		2.6	6	µA	+85°C		
		9	20	µA	+125°C		
	All devices	1.6	7	µA	-40°C	VDD = 3.3V(4) Regulator Disabled	
		2.8	9	µA	+25°C		
		4.1	10	µA	+85°C		
		17	40	µA	+125°C		
	All devices	60	150	µA	-40°C	VDD = 5V(5) Regulator Enabled	
		80	180	µA	+25°C		
		100	240	µA	+85°C		
		180	440	µA	+125°C		

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in a high-impedance state and tied to VDD or VSS, and all features that add delta current are disabled (such as WDT, SOSC oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: Standard, low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

4: Voltage regulator disabled (ENVREG = 0, tied to VSS, $\overline{RETEN}$ (CONFIG1L<0>) = 1).

5: Voltage regulator enabled (ENVREG = 1, tied to VDD, SRETEN (WDTCON<4>) = 1 and $\overline{RETEN}$ (CONFIG1L<0>) = 0).

6: LCD glass is not connected; resistor current is not included.

7: 48 MHz maximum frequency at 125°C.

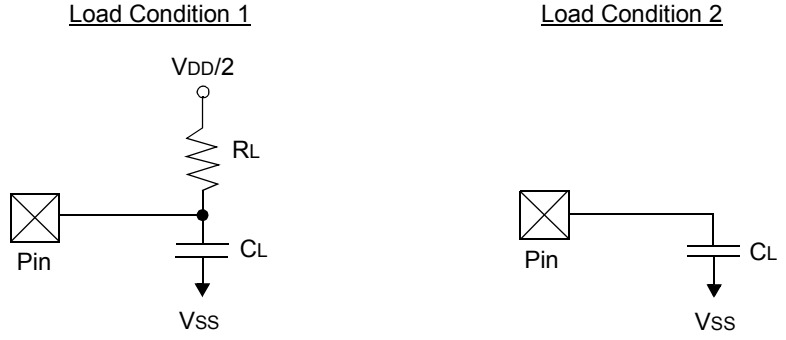
31.5.2 TIMING CONDITIONS

The temperature and voltages specified in Table 31-5 apply to all timing specifications unless otherwise noted. Figure 31-3 specifies the load conditions for the timing specifications.

TABLE 31-5: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended Operating voltage VDD range as described in **Section 31.1** and **Section 31.3**.

FIGURE 31-3: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

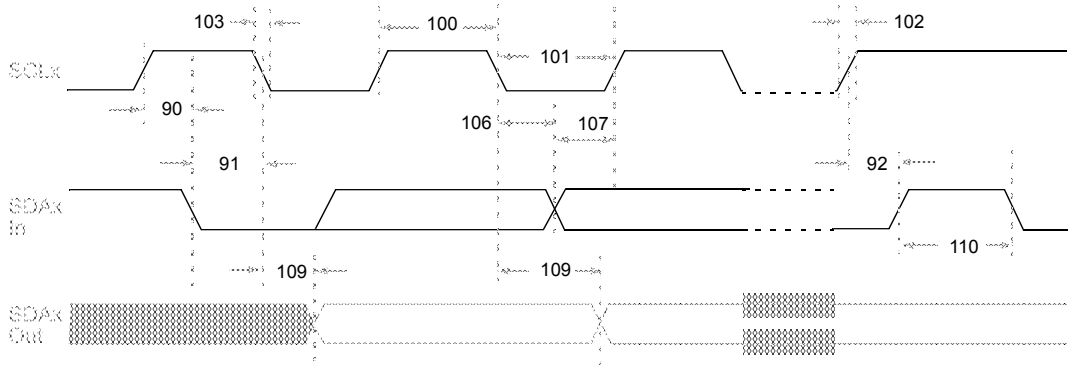


RL = 464Ω

CL = 50 pF for all pins except OSC2/CLKO/RA6 and including D and E outputs as ports

CL = 15 pF for OSC2/CLKO/RA6

FIGURE 31-16: I²C™ BUS DATA TIMING



Note: Refer to Figure 31-3 for load conditions.

TABLE 31-19: I²C™ BUS DATA REQUIREMENTS (SLAVE MODE)

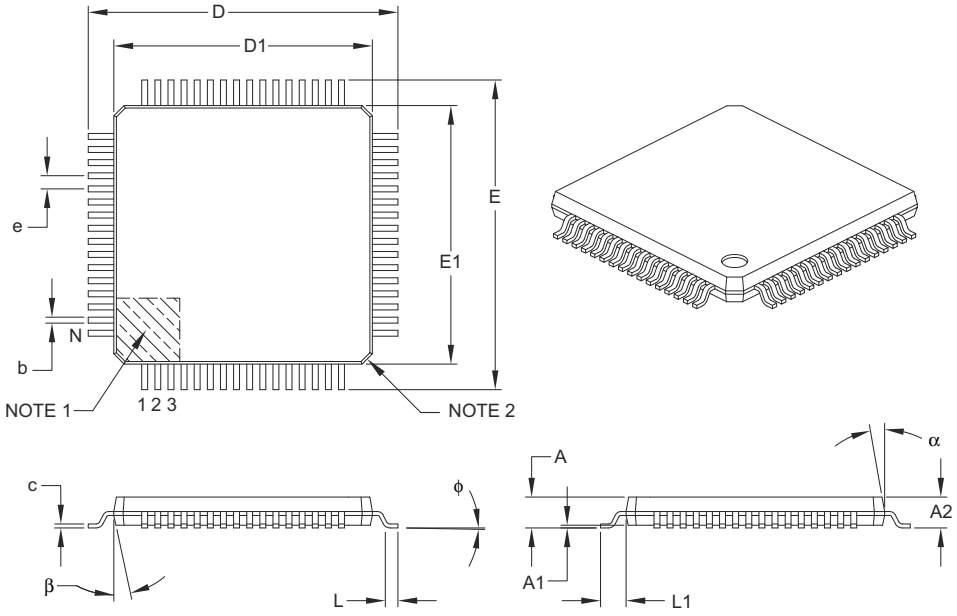
Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	4.0	—	µs	
			400 kHz mode	0.6	—	µs	
			MSSP module	1.5 TCY	—		
101	TLOW	Clock Low Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	1.3	—	µs	
			MSSP module	1.5 TCY	—		
102	TR	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
103	TF	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
90	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
91	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCLx to avoid unintended generation of Start or Stop conditions.

2: A Fast mode I²C™ bus device can be used in a Standard mode I²C bus system, but the requirement, TSU:DAT ≥ 250 ns, must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCLx signal. If such a device does stretch the LOW period of the SCLx signal, it must output the next data bit to the SDAx line, TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCLx line is released.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B